xLED

xLED-XIT-6030 Pin Fin LED Heat Sink Φ60mm for Xicato

Features VS Benefits

* The xLED-XIT-6030 Xicato Pin Fin LED Heat Sinks are specifically designed for luminaires using the Xicato LED engines.
* Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
* For spotlight and downlight designs from 500 to 1,600 lumen.
* Thermal resistance range Rth 5.0°C/W.
* Modular design with mounting holes foreseen for direct mounting of Xicato XSA/ XIM/ XTM modules.
* Diameter 60.0mm - standard height 30.0mm,Other heights on request.
* Forged from highly conductive aluminum.

Zhaga LED engine and radiator assembly is a unified future international standardization

* Below you find an overview of Seoul COB's and LED modules which standard fit on the Pin Fin LED Heat Sinks.
* In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of LED Pin Fin LED Heat Sink.

XICATO

Available Now
XIM 19mm
XTM 19mm

Coming Soon
XIM 9mm
XTM 9mm

Xicato LED Modules directly Mounting Options

Xicato XSM LED modules name :

XSM8027-xxxx ;	XSM9530-xxxx ;
XSM8030-xxxx ;	XSM9540-xxxx ;
XSM8040-xxxx ;	XSMV830-xxxx ;
XSM9527-xxxx ;	

Direct mounting with 3 screwsM3 x 12mm;
Green indicator marks.

Xicato XIM LED modules name :

XIM198027-xxx ;	XIM198040-xxx ;	XIM09-V9xxxxxx ;
XIM198030-xxx ;	XIM19V830-xxx ;	
XIM198035-xxx ;	XIM0980 xxxxxx ;	

Direct mounting with 3 screws M3 x 20mm;
Green indicator marks.

Xicato XTM LED modules:

XTM19-8027-xxx ;	XTM19-8040-xxx ;	XTM0995 xxxxxx ;
XTM19-8030-xxx ;	XTM19-V830-xxx ;	
XTM19-8035-xxx ;	XTM09-V9xxxxxx ;	

Direct mounting with 3 screws M3 x 10mm;
Green indicator marks.
Direct mounting by Zhaga mounting holes with 2 screws M3 x 8mm;
Red indicator marks.

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Mounting Options and Drawings & Dimensions

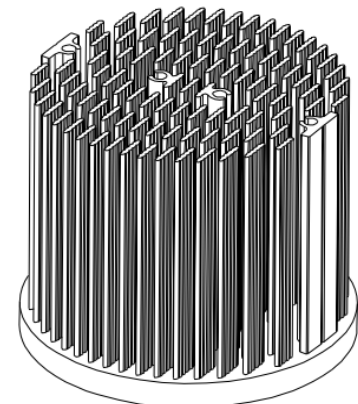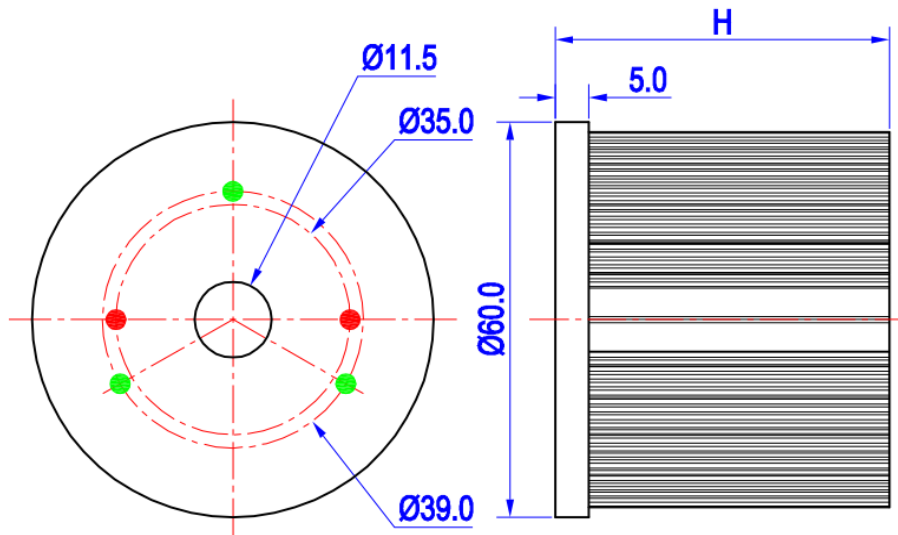**Example: xLED-XIT-6030-M3-B-1**

Example: xLED-XIT-6030-M3- `1` **-** `2`

`1` **Anodising Color**

B-Black

C-Clear

Z-Custom

`2` **Mounting Options - see graphics for details Combinations available**

Ex.order code - 12

means option 1 and 2 combined

Notes:

- Mentioned models are an extraction of full product range.

- For specific mechanical adaptations please contact MingfaTech.

- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	PART NUMBER	THREAD	THREAD DEPTH	THREAD HOLE DISTANCE
N	xLED-XIT-6030-M3-#-N	M3	6.5mm	39.0mm/ 3-@120°
1	xLED-XIT-6030-M3-#-1	M3	6.5mm	35.0mm/ 2-@180° (Zhaga Book 3)
2	xLED-XIT-6030-M3-#-2	M3	Φ11.5mm	Through-Hole

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The product deta table

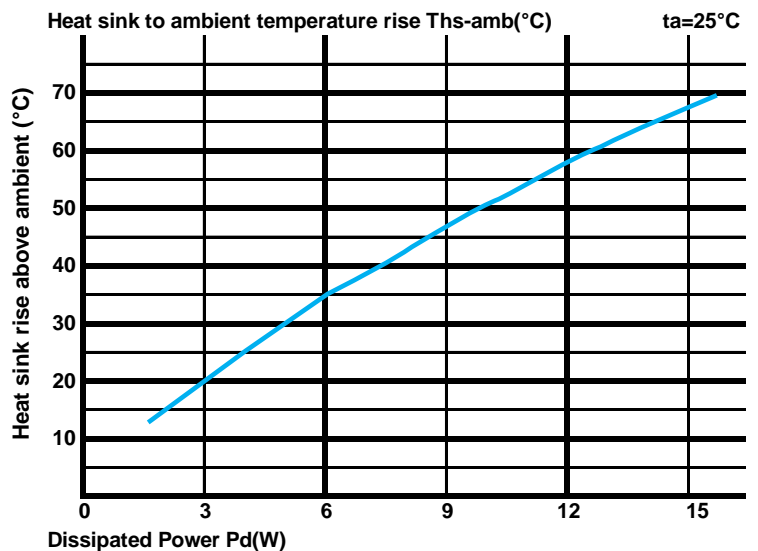| Model No.	xLED-XIT-6030
Heatsink Size	Φ60xH30mm
Heatsink Material	AL1070
Finish	Black Anodized
Weight (g)	80.0
Dissipated power (Ths-amb,50℃)	10.0 (W)
Cooling surface area (mm²)	40973
Thermal Resistance (Rhs-amb)	5.0 (℃/W)

The thermal data table

* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

*To calculate the dissipated power please use the following formula: $Pd = Pe \times (1-\eta L)$.

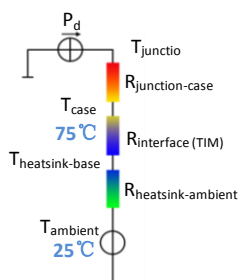Pd - Dissipated power ; Pe - Electrical power ; ηL = Light effciency of the LED module;

$Pd = Pe \times (1-\eta L)$		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)
		xLED-XIT-6030	
Dissipated Power Pd(W)	3.0	6.67	20.0
	6.0	5.67	34.0
	9.0	5.11	46.0
	12.0	4.83	58.0
	15.0	3.80	57.0

Heat sink to ambient temperature rise Ths-amb(°C)   **ta=25°C**

*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease,A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.

*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (Ths-Ta)/Pd$

θ - Thermal Resistance [℃/W] ; Ths - Heatsink temperature ; Ta - Ambient temperature ;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{junction-case}$, the thermal resistance of the TIM outside the package is $R_{interface (TIM)}$ [℃/W], the thermal resistance with the heat sink is $R_{heatsink-ambient}$ [℃/W], and the ambient temperature is $T_{ambient}$ [℃].

*Thermal resistances outside the package $R_{interface (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point.Thus, the following formula is also used:

$T_{junction} = (R_{junction-case} + R_{case-ambient}) \cdot Pd + T_{ambient}$